

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

SOIC WIDE

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TOTAL MASS (g) : 0.510686

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002823 | 1000000 | 5527.86230469 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.161470 | 975000 | 316182.71875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003975 | 24000 | 7783.6532031 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000050 | 300 | 97.9075775146 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000116 | 700 | 227.145584106 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.165611 | 1000000 | 324291.4375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.005671 | 1000000 | 11104.1542969 | | |
| | | External Plating Total: | | | | 0.005671 | 1000000 | 11104.1542969 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001325 | 1000000 | 2594.55078125 | | |
| Internal Plating Total: | | | | 0.001325 | 1000000 | 2594.55078125 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000865 | 750000 | 1693.80114746 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000288 | 250000 | 563.947692871 | | |
| Die Attach Total: | | | | 0.001153 | 1000000 | 2257.74902344 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.045043 | 135000 | 88201.0234375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.286939 | 860000 | 561870.0625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.001668 | 5000 | 3266.19702148 | | |
| | | Encapsulation Total: | | | | 0.333650 | 1000000 | 653337.3125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000453 | 1000000 | 887.042663574 | | |
| | | | | | TOTAL MASS (g) : | 0.510686 | | |